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FDS9933A

Dual P-Channel 2.5V Specified PowerTrench™ MOSFET

General Description

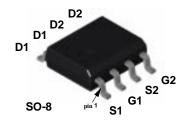
These P-Channel 2.5V specified MOSFETs are produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize the on-state resistance and yet maintain low gate charge for superior switching performance.

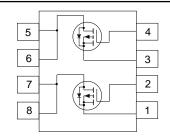
Applications

- Load switch
- DC/DC converter
- Motor drives

Features

- -3.8 A, -20 V. $R_{DS(on)} = 0.075~\Omega~$ @ $V_{GS} =$ -4.5 V $R_{DS(on)} = 0.105~\Omega~$ @ $V_{GS} =$ -2.5 V.
- Low gate charge (7nC typical).
- Fast switching speed.
- High performance trench technology for extremely low R_{DS(on)}.
- High power and current handling capability.





Absolute Maximum Ratings TA=25°C unless otherwise noted

Symbol	Parameter		FDS9933A	Units
V _{DSS}	Drain-Source Voltage		-20	V
V _{GSS}	Gate-Source Voltage		<u>±</u> 8	V
I _D	Drain Current - Continuous	(Note 1a)	-3.8	А
	- Pulsed		-20	
P _D	Power Dissipation for Dual Operation		2.0	W
	Power Dissipation for Single Operation	(Note 1a)	1.6	
		(Note 1b)	1.0	
		(Note 1c)	0.9	
TJ, Tsta	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta^{JA}}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	78	°C/W
$R_{ heta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	40	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
FDS9933A	FDS9933A	13"	12mm	2500 units

Max

Units

Min

Тур

DMOS Electrical Characteristics

Parameter

T_A = 25°C unless otherwise noted

Test Conditions

Off Cha	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	-20			V
ABVDSS ATJ	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, Referenced to 25°C		-16		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -16 \text{ V}, V_{GS} = 0 \text{ V}$			-1	μA
I _{GSSF}	Gate-Body Leakage, Forward	$V_{GS} = 8 \text{ V}, V_{DS} = 0 \text{ V}$			100	nA
I _{GSSR}	Gate-Body Leakage, Reverse	$V_{GS} = -8 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA

On Characteristics (Note 2)

Symbol

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	-0.4	-0.8	-1.5	٧
<u>A</u> VGS(th) ΔTJ	Gate Threshold Voltage Temperature Coefficient	I_D = -250 μ A, Referenced to 25°C		2.5		mV/∘C
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = -4.5 \text{ V}, I_D = -3.8 \text{ A}$ $V_{GS} = -4.5 \text{ V}, I_D = -3.8 \text{ A}, T_J = 125 \circ \text{C}$ $V_{GS} = -2.5 \text{ V}, I_D = -3.3 \text{ A}$		0.058 0.086 0.084	0.075 0.12 0.105	Ω Ω Ω
I _{D(on)}	On-State Drain Current	$V_{GS} = -4.5 \text{ V}, V_{DS} = -5.0 \text{ V}$	-10			Α
g _{FS}	Forward Transconductance	$V_{DS} = -4.5 \text{ V}, I_{D} = -3.8 \text{ A}$		10		S

Dynamic Characteristics

C _{iss}	Input Capacitance	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1.0 \text{ MHz}$	600	pF
Coss	Output Capacitance		175	pF
C _{rss}	Reverse Transfer Capacitance		80	pF

Switching Characteristics (Note 2)

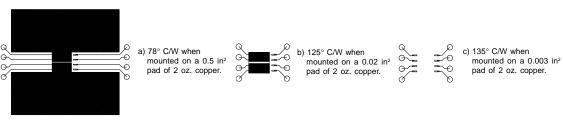
t _{d(on)}	Turn-On Delay Time	$V_{DD} = -5 \text{ V}, I_D = -0.5 \text{ A},$	6	12	ns
t _r	Turn-On Rise Time	V_{GS} = -4.5 V, R_{GEN} = 6.0 Ω	9	18	ns
t _{d(off)}	Turn-Off Delay Time		31	50	ns
t _f	Turn-Off Fall Time		28	42	ns
Qg	Total Gate Charge	$V_{DS} = -10 \text{ V}, I_{D} = -3.8 \text{ A},$	7	10	nC
Q _{gs}	Gate-Source Charge	$V_{GS} = -4.5 \text{ V}$	1.3		nC
Q_{gd}	Gate-Drain Charge		2		nC

Drain-Source Diode Characteristics and Maximum Ratings

Is	Maximum Continuous Drain-Source Diode Forward Current			-1.3	Α
V_{SD}	Drain-Source Diode Forward	$V_{GS} = 0 \text{ V}, I_{S} = -1.3 \text{ A}$ (Note 2)	-0.75	-1.2	V

Notes:

1: R_{0,IA} is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0,IC} is guaranteed by design while R_{0,IA} is determined by the user's board design.



Scale 1 : 1 on letter size paper

2: Pulse Test: Pulse Width $\leq 300~\mu s$, Duty Cycle $\leq 2.0\%$

FDS9933A Rev. C

Typical Characteristics (continued)

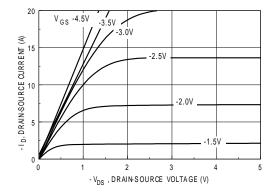


Figure 1. On-Region Characteristics.

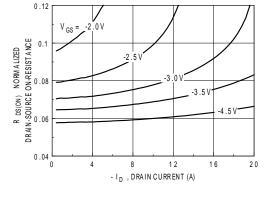


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

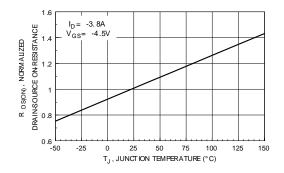


Figure 3. On-Resistance Variation with Temperature.

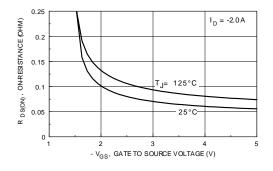


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

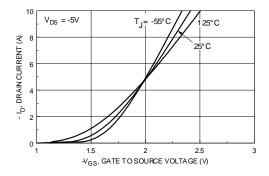


Figure 5. Transfer Characteristics.

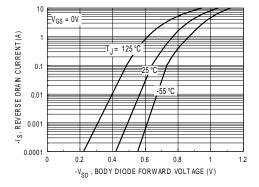
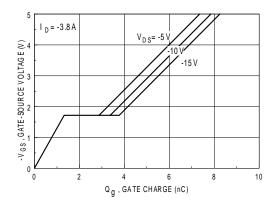


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics (continued)



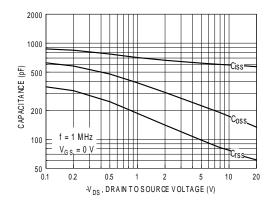
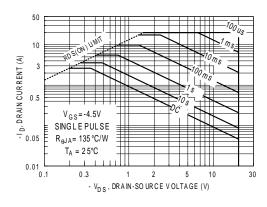


Figure 7. Gate Charge Characteristics.

Figure 8. Capacitance Characteristics.



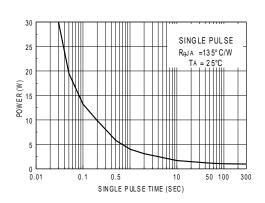


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

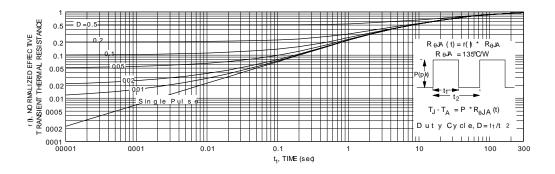


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1c. Transient themal response will change depending on the circuit board design.

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